

ABSTRACT

An electronic chip device includes an interface support film having a support film and at least one flat conductive interface placed on the support film, as well as a microcircuit connected to the interface. The interface support film possesses such properties that it can be creased or folded on itself without deterioration. The support film possesses a thickness of less than 75  $\mu\text{m}$ , the best results being obtained with a thickness of between 10  $\mu\text{m}$  and 30  $\mu\text{m}$ . Preferably the support film is selected from among polypropylene (PP), polyethylene (PE), polyethylene teraphthalate (PET). In one embodiment, the device includes a compensation film placed on the support film. The compensation film has a recess containing the microcircuit and its connections. The recess can contain a material to encapsulate the microcircuit and its connections.

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